

MCB0603 Series

Specification

Product Name | Chip Ferrite Bead | Series | MCB 0603

Size | EIAJ 0603





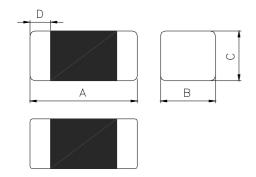


Chip Ferrite Bead (MCB0603 Series) Engineering Spec.

1.Features

- Monolithic inorganic material construction.
- > Closed magnetic circuit avoids crosstalk.
- S.M.T. type.
- > Suitable for reflow soldering.
- Shapes and dimensions follow E.I.A. spec.
- > Available in various sizes.
- Excellent solder ability and heat resistance.
- High reliability.
- 100% Lead(Pb) & Halogen- Free and RoHS compliant.

2.Dimensions



TYPE	Dimension		
Α	0.60±0.03		
B 0.30±0.03			
c 0.30±0.03			
D 0.15±0.05			
Unit: mm			

3.Part Numbering

<u>MCB</u>	<u>0603</u>	<u>B</u>	<u>10</u>	<u>0</u>	<u>E</u>	<u>B</u>	<u>P</u>
1	2	3	4	5	6	7	8

- 1 Series Name
- 2 Dimensions L*W
- 3 Material Code
- 4 Impedance(Ω) ± 25% (ex: 100=10Ω; 121=120Ω)
- 5 Fixed Decimal Point
- 6 Rated Current Code

A=50mA	B=80mA	C=100mA	D=150mA	E=200mA	F=300mA
G=400mA	H=500mA	I =600mA	J =700mA	K=800mA	

- 7 Soldering: Green Parts: A— Soldering Lead-Free B— Lead-Free for whole chip
- 8 Packaging: P Embossed paper tape, 7" reel.

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■ Www.inpaq.com.tw; www.inpaqgp.com

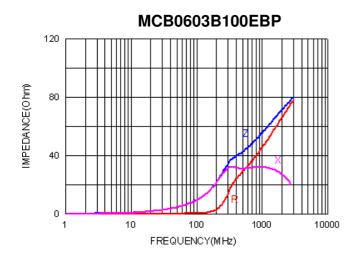


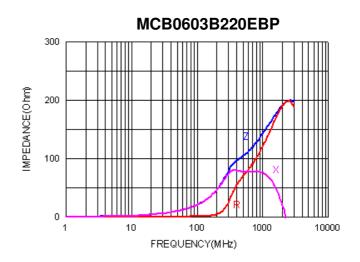
Specification

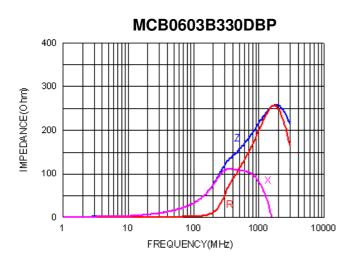
Part No.	Impedance(Ω) +/-25%	Test Freq. (MHz)	DCR(Ω) (Max.)	Rated Current (mA)
MCB0603B100EBP	10	100	0.25	200
MCB0603B220EBP	22	100	0.45	200
MCB0603B330DBP	33	100	0.55	150
MCB0603B470DBP	47	100	0.70	150
MCB0603B560CBP	56	100	1.00	100
MCB0603B800CBP	80	100	1.30	100
MCB0603B121CBP	120	100	1.50	100
MCB0603H600EBP	60	100	0.25	200
MCB0603H121EBP	120	100	0.40	200
MCB0603H241EBP	240	100	0.80	200
MCB0603H471CBP	470	100	1.05	100
MCB0603H601CBP	600	100	1.20	100
MCB0603W220HBP	22	100	0.065	500
MCB0603W330HBP	33	100	0.07	500
MCB0603W800EBP	80	100	0.40	200
MCB0603W121EBP	120	100	0.45	200
MCB0603W241EBP	240	100	0.65	200
MCB0603W601DBP	600	100	1.20	150
MCB0603W102EBP	1000	100	1.15	200

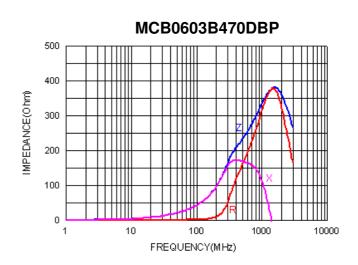


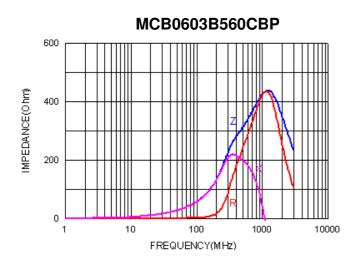
Impedance Frequency Characteristics(Typical)

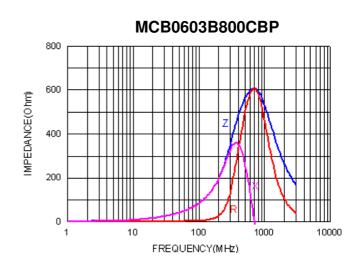












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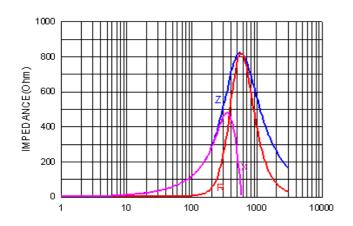
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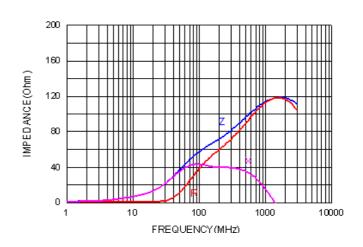
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MCB0603B121CBP

MCB0603H600EBP



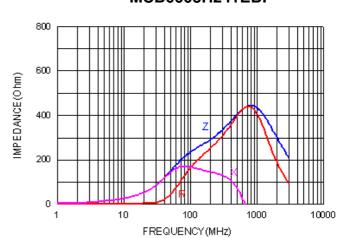


MCB0603H121EBP

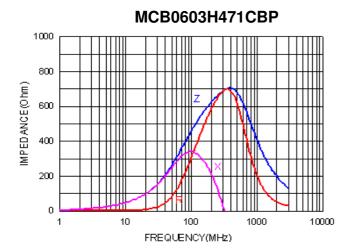
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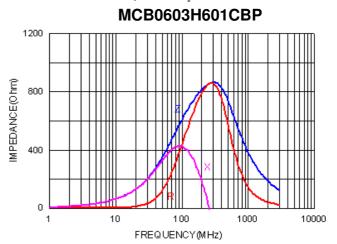
FREQUENCY(MHz)

MCB0603H241EBP

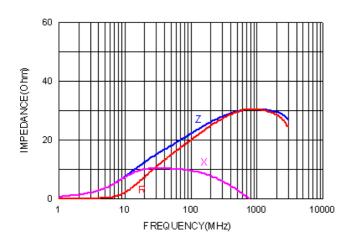




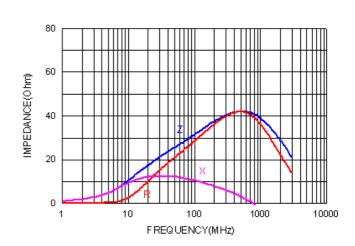


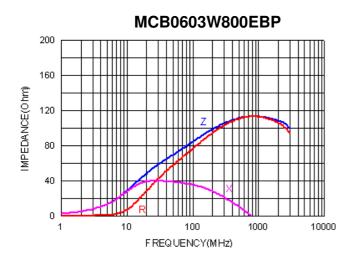


MCB0603W220HBP

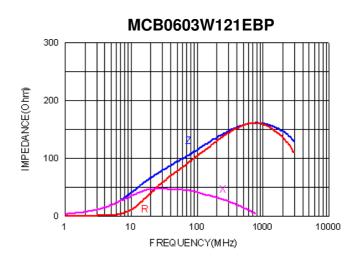


MCB0603W330HBP





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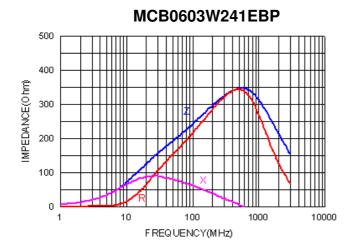


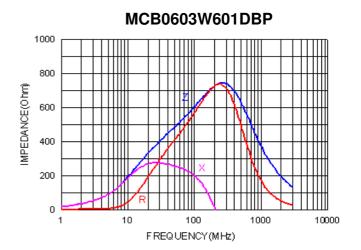
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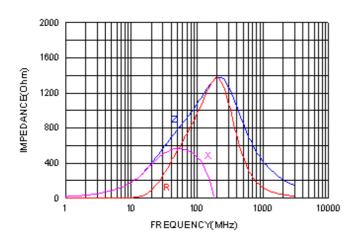
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MCB0603W102EBP





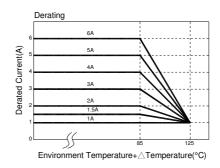
5. Reliability and Test Condition

Item		Test Condition
Operating Temperature	-40~+125°C (Including self-temperature rise)	
Transportation Storage Temperature	-40~+125°℃	For long storage conditions, please see the Application Notice
Impedance (Z)		Agilent4291
Inductance (Ls)		Agilent E4991
Q Factor		Agilent4287
DC Resistance	Refer to standard electrical characteristics list	Agilent16192
DC nesistance		Agilent 4338 DC Power Supply
Rated Current		Over Rated Current requirements, there will be some risk
Temperature Rise Test	Rated Current < 1A Δ T 20°C Max Rated Current \geq 1A Δ T 40°C Max	Applied the allowed DC current. Temperature measured by digital surface thermometer.
Resistance to Soldering Heat	Appearance: No damage. Impedance: within±15% of initial value Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within±15% of initial value and shall not exceed the specification value	Preheat: 150°C,60sec. Solder: Sn99.5,60sec. Solder tamperature: 260±5°C Flux for lead free: Rosin. 9.5% Temperature ramp/immersion and immersion rate: 25±6 mm/s Dip time: 10±1sec. Depth: completely cover the termination.
Solderability	More than 95% of the terminal electrode should be covered with solder.	Preheat: 150°C,60sec. Solder: Sn99.5%-Cu0.5% Solder tamperature: 245±5°C Flux for lead free: Rosin. 9.5% Depth: completely cover the termination. Dip time: 4±1sec.
Terminal strength	Appearance: No damage. Impedance: within±15% of initial value Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020D Classification Reflow Profiles) Component mounted on a PCB apply a force (>0805:1kg <=0805:0.5kg)to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to shock the component being tested.
Bending	Appearance: No damage. Impedance: within±10% of initial value Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within±15% of initial value and shall not exceed the specification value	Shall be mounted on a FR4 substrate of the following dimensions:>=0805:40x100x1.2mm
Vibration Test	Appearance: No damage. Impedance: within±15% of initial value Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020D Classification Reflow Profiles) Oscillation Frequency: 10~2K~10Hz for 20 minutes Equipment: Vibration checker Total Amplitude:1.52mm±10% Testing Time: 12 hours(20 minutes, 12 cycles each of 3 orientations)



Item	Performance	Test Condition				
		Test condition:				
Shock	Appearance : No damage. Impedance : within±15% of initial value Inductance : within±10% of initial value			Normal duration (D) (ms)	Wave form	Velocity change (Vi)ft/sec
	Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value	SMD	1,500	0.5	Half-sine	15.4
		Lead	100	6	Half-sine	12.3
Life test	Appearance: no damage. Impedance: within±15%of initial value. Inductance: within±10%of initial value. Q: Shall not exceed the specification value.	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020D Classification Reflow Profiles) Temperature: 125±2°C (bead), 85±2°C (inductor) Applied current: rated current. Duration: 1000±12hrs. Measured at room temperature after placing for 24±2 hrs. Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020D Classification				
Load Humidity	RDC: within ±15% of initial value and shall not exceed the specification value	Reflow Profiles) Humidity: 85±2%R.H. Temperature: 85±2°C. Duration: 1000hrs Min. with 100% rated current. Measured at room temperature after placing for 24±2 hrs.				
Thermal shock	Appearance: no damage. Impedance: within±15%of initial value. Inductance: within±10%of initial value. Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020D Classification Reflow Profiles) Condition for 1 cycle Step1: -40±2°C 30±5 min. Step2: 25±2°C ≤0.5min Step3: +105±2°C 30±5min. Number of cycles: 500 Measured at room temperature after placing for 24±2 hrs.				
Insulation Resistance	nce IR>1GΩ Chip Inducto Test Voltage				r 30Sec.	

**Derating Curve

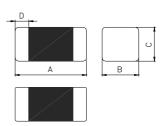


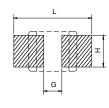


6. Soldering and Mounting

6-1. Recommended PC Board Pattern

Chip Size						d Patterns	-	
мсв	Туре	A(mm)	B(mm)	C(mm)	D(mm)	L(mm)	G(mm)	H(mm)
IVICB	0603	0.6±0.03	0.30±0.03	0.30±0.03	0.15±0.05	0.80	0.30	0.30





6-2. Soldering

Mildly activated rosin fluxes are preferred. The terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

If wave soldering is used ,there will be some risk.

Re-flow soldering temperatures below 240 degrees, there will be non-wetting risk

6-2.1 Lead Free Solder re-flow:

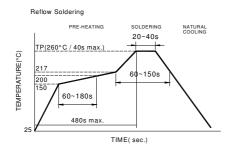
Recommended temperature profiles for lead free re-flow soldering in Figure 1. (Refered to J-STD-020C)

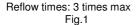
6-2.2 Soldering Iron:

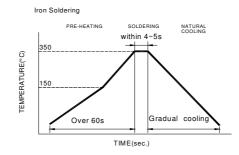
Products attachment with a soldering iron is discouraged due to the inherent process control limitations. If a soldering iron must be employed the following precautions are recommended. for Iron Soldering in Figure 2.

- \cdot Preheat circuit and products to 150 $\!\!\!\!^{\circ}_{\circ}$
- · Never contact the ceramic with the iron tip
- · Use a 20 watt soldering iron with tip diameter of 1.0mm

- · 350℃ tip temperature (max)
- 1.0mm tip diameter (max)
- Limit soldering time to 4~5sec.





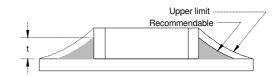


Iron Soldering times: 1 times max Fig.2

6-2.3 Solder Volume:

Accordingly increasing the solder volume, the mechanical stress to product is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance. Solder shall be used not to be exceed as shown in right side:

Minimum fillet height = soldering thickness + 25% product height



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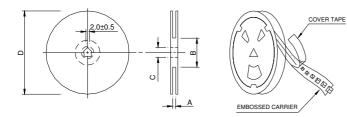
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7. Packaging Information

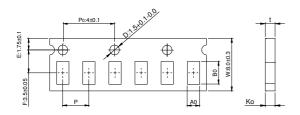
7-1. Reel Dimension



Туре	A(mm)	B(mm)	C(mm)	D(mm)
7"x8mm	10±1.5	50 or more	13±0.2	178±2

7-2.1 Tape Dimension / 8mm

■Material of taping is paper



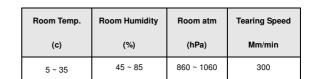
Size	B0(mm)	A0(mm)	K0(mm)	P(mm)	t(mm)
060303	0.70±0.06	0.40±0.06	0.45max	2.0±0.05	0.45max

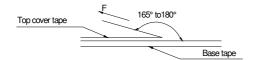
7-3. Packaging Quantity

Chip Size	060303		
Chip / Reel	15000		
Inner box	75000		
Middle box	375000		
Carton	750000		

7-4. Tearing Off Force

The force for tearing off cover tape is 15 to 60 grams in the arrow direction under the following conditions.





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